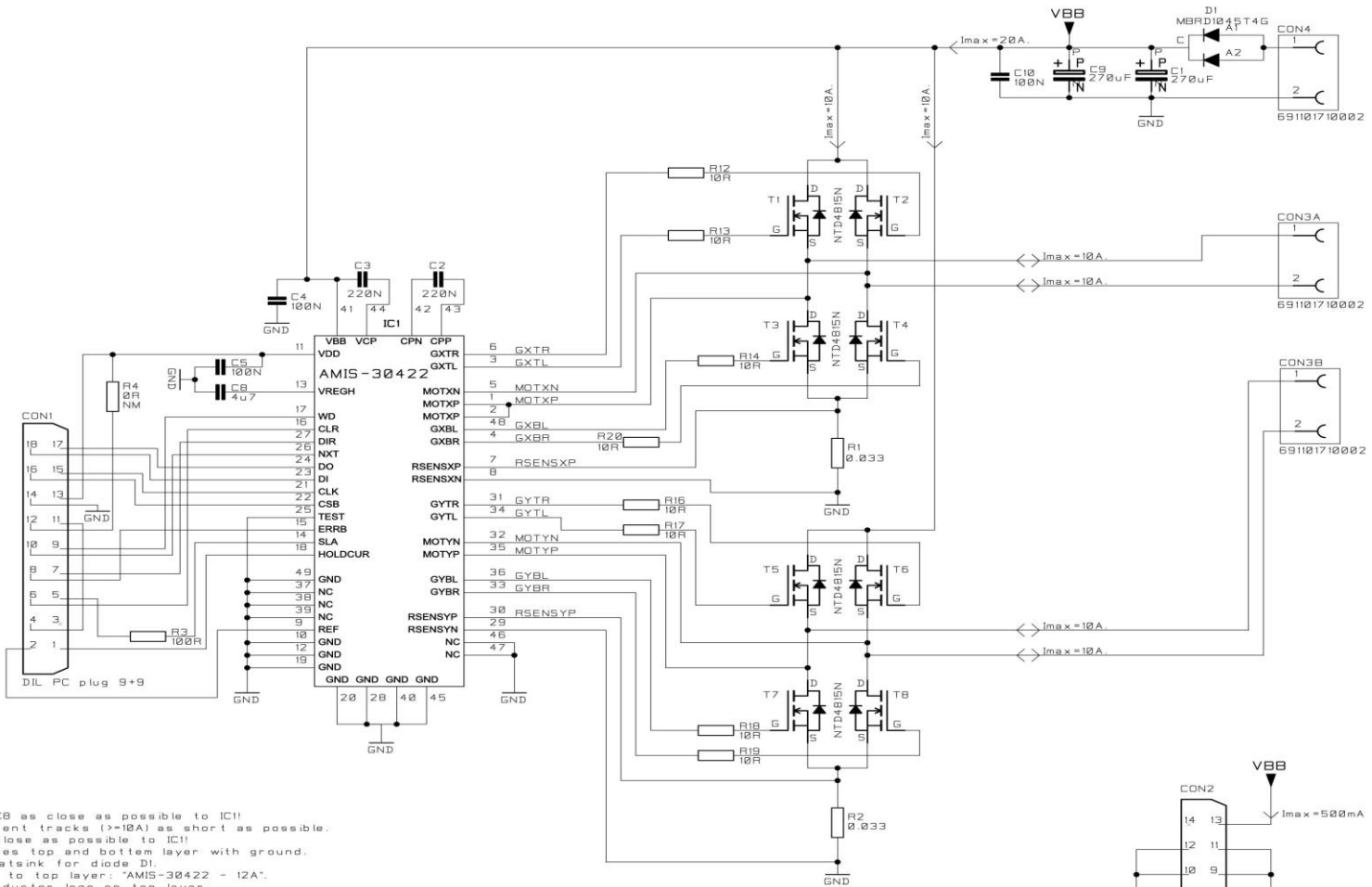
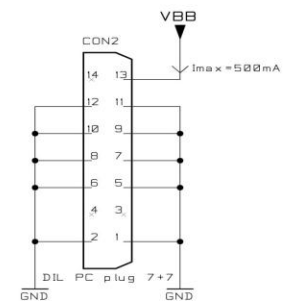




# Schematic for the AMIS30422DBGVB Evaluation Board



- Comments:
- C2 ... C5 and C8 as close as possible to IC!
  - Keep high current tracks (>10A) as short as possible.
  - R1 and R2 as close as possible to IC!
  - Fill empty spaces top and bottom layer with ground.
  - Foresee PCB heatsink for diode D1.
  - Add next text to top layer: "AMIS-30422 - 12A".
  - Add ON Semiconductor logo on top layer.
  - Add Pb-free label on top layer.
  - Add next text to bottom layer: "AMIS\_REV1\_3042X\_V4".
  - Two layer PCB!
  - Write next text at CON4: "POWER".
  - Make a clear marking of + and - connections of CON4 (Silkscreen).
  - CON3 must be stuffed on bottom layer.
  - Write next text at CON3: "MOTOR CONNECTOR". This may be done at top silkscreen if there is no bottom silkscreen.
  - Don't write "CON3" and "CON4" in silkscreen.
  - R1/R2: make a good connection to ground to get heat out of package.
  - Foresee sufficient vias under exposed paddle of IC1 to get heat out of package. Make a good connection with ground layer (PCB heatsink).



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